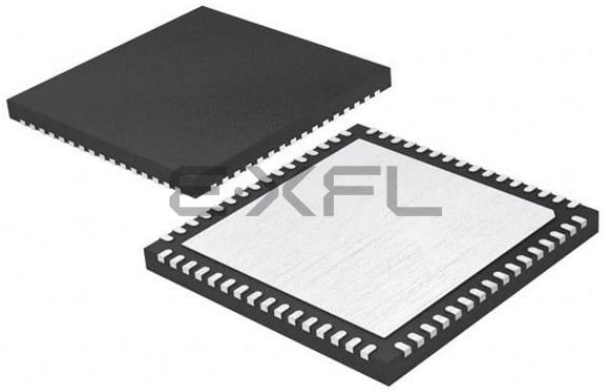
Microchip Technology - PIC24HJ128GP206A-E/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp206a-e-mr

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TABLE 4-31: SYSTEM CONTROL REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	—	—	—	—	—	VREGS	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	xxxx(1)
OSCCON	0742	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	—	LOCK	—	CF	—	LPOSCEN	OSWEN	0300(2)
CLKDIV	0744	ROI	DOZE<2:0>			DOZEN	FRCDIV<2:0>			PLLPOST<1:0>		—	PLLPRE<4:0>					3040
PLLFBD	0746	—	—	—	—	—	—	—	PLLDIV<8:0>									0030
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.
Note 1: RCON register Reset values dependent on type of Reset.
2: OSCCON register Reset values dependent on the FOSC Configuration bits and by type of Reset.

TABLE 4-32: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	—	—	—	—	—	—	ERASE	—	—	NVMOP<3:0>				0000(1)
NVMKEY	0766	—	—	—	—	—	—	—	—	NVMKEY<7:0>								0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.
Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-33: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	T5MD	T4MD	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	C2MD	C1MD	AD1MD	0000
PMD2	0772	IC8MD	IC7MD	IC6MD	IC5MD	IC4MD	IC3MD	IC2MD	IC1MD	OC8MD	OC7MD	OC6MD	OC5MD	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0774	T9MD	T8MD	T7MD	T6MD	—	—	—	—	—	—	—	—	—	—	I2C2MD	AD2MD	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

7.3 Interrupt Control and Status Registers

PIC24HJXXXGPX06A/X08A/X10A devices implement a total of 30 registers for the interrupt controller:

- INTCON1
- INTCON2
- IFS0 through IFS4
- IEC0 through IEC4
- IPC0 through IPC17
- INTTREG

Global interrupt control functions are controlled from INTCON1 and INTCON2. INTCON1 contains the Interrupt Nesting Disable (NSTDIS) bit as well as the control and status flags for the processor trap sources. The INTCON2 register controls the external interrupt request signal behavior and the use of the Alternate Interrupt Vector Table.

The IFS registers maintain all of the interrupt request flags. Each source of interrupt has a Status bit, which is set by the respective peripherals or external signal and is cleared via software.

The IEC registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

The IPC registers are used to set the interrupt priority level for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

The INTTREG register contains the associated interrupt vector number and the new CPU interrupt priority level, which are latched into vector number (VECNUM<6:0>) and Interrupt level (ILR<3:0>) bit fields in the INTTREG register. The new interrupt priority level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence that they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having vector number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0>, and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

Although they are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. The CPU STATUS register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU interrupt priority level. The user can change the current CPU priority level by writing to the IPL bits.

The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU priority level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-1 through Register 7-32.

REGISTER 7-7: IFS2: INTERRUPT FLAG STATUS REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T6IF	DMA4IF	—	OC8IF	OC7IF	OC6IF	OC5IF	IC6IF
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC5IF	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **T6IF:** Timer6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **DMA4IF:** DMA Channel 4 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 13 **Unimplemented:** Read as '0'

bit 12 **OC8IF:** Output Compare Channel 8 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **OC7IF:** Output Compare Channel 7 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10 **OC6IF:** Output Compare Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 9 **OC5IF:** Output Compare Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8 **IC6IF:** Input Capture Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **IC5IF:** Input Capture Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **IC4IF:** Input Capture Channel 4 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **IC3IF:** Input Capture Channel 3 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **DMA3IF:** DMA Channel 3 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **C1IF:** ECAN1 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 7-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
C2TXIF	C1TXIF	DMA7IF	DMA6IF	—	U2EIF	U1EIF	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **C2TXIF:** ECAN2 Transmit Data Request Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **C1TXIF:** ECAN1 Transmit Data Request Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **DMA7IF:** DMA Channel 7 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **DMA6IF:** DMA Channel 6 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **Unimplemented:** Read as '0'

bit 2 **U2EIF:** UART2 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **U1EIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **Unimplemented:** Read as '0'

REGISTER 7-19: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	CNIP<2:0>			—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	MI2C1IP<2:0>			—	SI2C1IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **CNIP<2:0>:** Change Notification Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as '0'

bit 6-4 **MI2C1IP<2:0>:** I2C1 Master Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **SI2C1IP<2:0>:** I2C1 Slave Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 7-26: IPC11: INTERRUPT PRIORITY CONTROL REGISTER 11

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T6IP<2:0>			—	DMA4IP<2:0>		
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	OC8IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T6IP<2:0>:** Timer6 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **DMA4IP<2:0>:** DMA Channel 4 Data Transfer Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **OC8IP<2:0>:** Output Compare Channel 8 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the PIC24HJXXXGPX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 9. "Watchdog Timer and Power-Saving Modes"** (DS70196) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJXXXGPX06A/X08A/X10A devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. PIC24HJXXXGPX06A/X08A/X10A devices can manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep and Idle modes
- Software-controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24HJXXXGPX06A/X08A/X10A devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24HJXXXGPX06A/X08A/X10A devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembly syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode has these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled
- The LPRC clock continues to run in Sleep mode if the WDT is enabled
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode
- Some device features or peripherals may continue to operate in Sleep mode. This includes items such as the input change notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation is disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep, the processor restarts with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV  #IDLE_MODE     ; Put the device into IDLE mode
```

17.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the PIC24HJXXXGPX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Inter-Integrated Circuit (I^2C) module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The PIC24HJXXXGPX06A/X08A/X10A devices have up to two I^2C interface modules, denoted as I2C1 and I2C2. Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module 'x' (x = 1 or 2) offers the following key features:

- I^2C interface supporting both master and slave operation
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7-bit and 10-bit addressing
- I^2C Port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation; detects bus collision and will arbitrate accordingly

17.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I^2C module can operate either as a slave or a master on an I^2C bus.

The following types of I^2C operation are supported:

- I^2C slave operation with 7-bit addressing
- I^2C slave operation with 10-bit addressing
- I^2C master operation with 7-bit or 10-bit addressing

For details about the communication sequence in each of these modes, please refer to the *"dsPIC33F/PIC24H Family Reference Manual"*.

REGISTER 20-5: ADxCHS123: ADCx INPUT CHANNEL 1, 2, 3 SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NB<1:0>		CH123SB
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CH123NA<1:0>		CH123SA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-9 **CH123NB<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample B bits

When AD12B = 1, CHxNB is: U-0, Unimplemented, Read as '0'

11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11

10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8

0x = CH1, CH2, CH3 negative input is VREF-

bit 8 **CH123SB:** Channel 1, 2, 3 Positive Input Select for Sample B bit

When AD12B = 1, CHxSB is: U-0, Unimplemented, Read as '0'

1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5

0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

bit 7-3 **Unimplemented:** Read as '0'

bit 2-1 **CH123NA<1:0>:** Channel 1, 2, 3 Negative Input Select for Sample A bits

When AD12B = 1, CHxNA is: U-0, Unimplemented, Read as '0'

11 = CH1 negative input is AN9, CH2 negative input is AN10, CH3 negative input is AN11

10 = CH1 negative input is AN6, CH2 negative input is AN7, CH3 negative input is AN8

0x = CH1, CH2, CH3 negative input is VREF-

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample A bit

When AD12B = 1, CHxSA is: U-0, Unimplemented, Read as '0'

1 = CH1 positive input is AN3, CH2 positive input is AN4, CH3 positive input is AN5

0 = CH1 positive input is AN0, CH2 positive input is AN1, CH3 positive input is AN2

24.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC24HJXXXGPX06A/X08A/X10A electrical characteristics. Additional information is provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC24HJXXXGPX06A/X08A/X10A family are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS} **(4)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$ **(4)** ..... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} < 3.0V$ **(4)** ..... -0.3V to 3.6V
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin **(2)** ..... 250 mA
Maximum current sourced/sunk by any 2x I/O pin **(3)** ..... 8 mA
Maximum current sourced/sunk by any 4x I/O pin **(3)** ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin **(3)** ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports **(2)** ..... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 24-2).

3: Exceptions are CLKOUT, which is able to sink/source 25 mA, and the V_{REF}+, V_{REF}-, SCLx, SDAx, PGECx and PGEDx pins, which are able to sink/source 12 mA.

4: See the “**Pin Diagrams**” section for 5V tolerant pins.

TABLE 24-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Operating Current (IDD)(1)						
DC20d	27	30	mA	-40°C	3.3V	10 MIPS
DC20a	27	30	mA	+25°C		
DC20b	27	30	mA	+85°C		
DC20c	27	35	mA	+125°C		
DC21d	36	40	mA	-40°C	3.3V	16 MIPS
DC21a	37	40	mA	+25°C		
DC21b	38	45	mA	+85°C		
DC21c	39	45	mA	+125°C		
DC22d	43	50	mA	-40°C	3.3V	20 MIPS
DC22a	46	50	mA	+25°C		
DC22b	46	55	mA	+85°C		
DC22c	47	55	mA	+125°C		
DC23d	65	70	mA	-40°C	3.3V	30 MIPS
DC23a	65	70	mA	+25°C		
DC23b	65	70	mA	+85°C		
DC23c	65	70	mA	+125°C		
DC24d	84	90	mA	-40°C	3.3V	40 MIPS
DC24a	84	90	mA	+25°C		
DC24b	84	90	mA	+85°C		
DC24c	84	90	mA	+125°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- CPU executing `while(1)` statement
- JTAG is disabled

2: These parameters are characterized but not tested in manufacturing.

3: Data in “Typ” column is at 3.3V, +25ºC unless otherwise stated.

TABLE 24-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O pins	VSS	—	0.2 VDD	V	
DI15		$\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI16		I/O Pins with OSC1 or SOSCI	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I2C	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with I2C	VSS	—	0.8 V	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant(4) I/O Pins 5V Tolerant(4)	0.7 VDD 0.7 VDD	— —	VDD 5.5	V V	
DI28		SDAx, SCLx	0.7 VDD	—	5.5	V	SMBus disabled
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**CNx Pull-up Current**					
DI30			50	250	400	μA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Pins 5V Tolerant(4)	—	—	±2	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(4)	—	—	±1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(4)	—	—	±2	μA	Shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(4)	—	—	±3.5	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(4)	—	—	±8	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{MCLR}$	—	—	±2	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±2	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **"Pin Diagrams"** for a list of 5V tolerant pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

24.2 AC Characteristics and Timing Parameters

This section defines PIC24HJXXXGPX06A/X08A/X10A AC characteristics and timing parameters.

TABLE 24-14: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in Table 24-1.

FIGURE 24-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

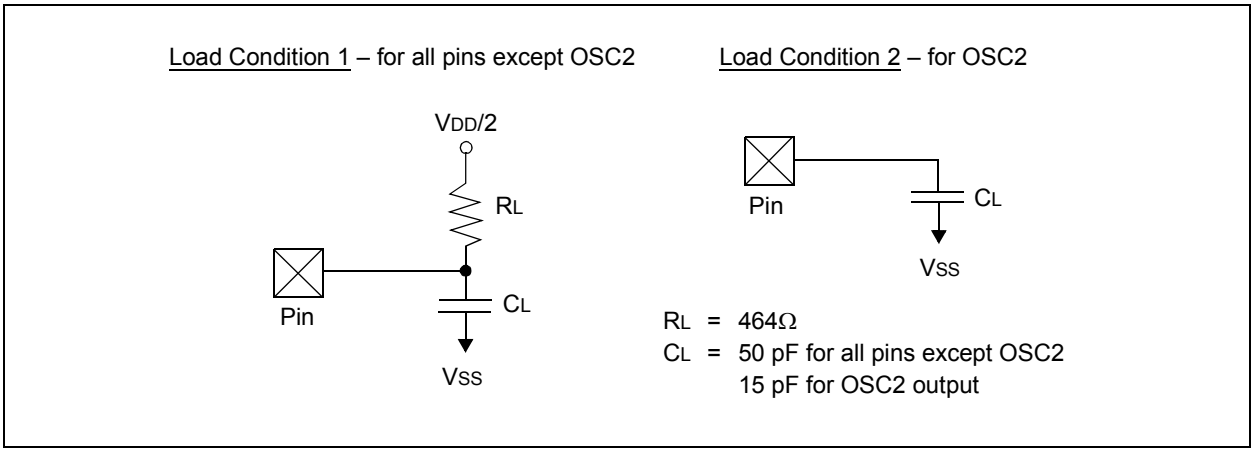


TABLE 24-15: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
DO50	COSCO	OSC2/SOSCO pin	—	—	15	pF	In XT and HS modes when external clock is used to drive OSC1
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C™ mode

TABLE 24-35: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCK clock generated by the Master must not violate this specificiation.

4: Assumes 50 pF load on all SPIx pins.

TABLE 24-36: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode(2)	—	400	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**See Note 3**

Note 1: BRG is the value of the I^2C Baud Rate Generator. Refer to **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195) in the "*PIC24H Family Reference Manual*". Please see the Microchip web site (www.microchip.com) for the latest PIC24H Family Reference Manual chapters.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

25.1 High Temperature DC Characteristics

TABLE 25-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temperature Range (in °C)	Max MIPS
			PIC24HJXXXGPX06A/X08A/X10A
HDC5	VBOR to 3.6V(1)	-40°C to +150°C	20

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules such as the ADC will have degraded performance. Device functionality is tested but not characterized. Refer to parameter BO10 in Table 24-11 for the minimum and maximum BOR values.

TABLE 25-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
High Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+155	°C
Operating Ambient Temperature Range	TA	-40	—	+150	°C
Power Dissipation: Internal chip power dissipation: PINT = VDD x (IDD - Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD - VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ - TA)/θJA			W

TABLE 25-3: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
Operating Voltage							
HDC10	**Supply Voltage**						
	VDD	—	3.0	3.3	3.6	V	-40°C to +150°C

TABLE 25-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	Typical	Max	Units	Conditions		
Power-Down Current (IPD)						
HDC60e	250	2000	μA	+150°C	3.3V	Base Power-Down Current(1,3)

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 25-14: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Reference Inputs							
HAD08	IREF	Current Drain	— —	250 —	600 50	μA μA	ADC operating, See **Note 1** ADC off, See **Note 1**

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 25-15: ADC MODULE SPECIFICATIONS (12-BIT MODE)(3)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF-(1)							
AD23a	GERR	Gain Error	—	5	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24a	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF-(1)							
AD23a	GERR	Gain Error	2	10	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24a	EOFF	Offset Error	2	5	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (12-bit Mode)(2)							
HAD33a	FNYQ	Input Signal Bandwidth	—	—	200	kHz	—

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

TABLE 25-16: ADC MODULE SPECIFICATIONS (10-BIT MODE)(3)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with external VREF+/VREF-(1)							
AD23b	GERR	Gain Error	—	3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24b	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with internal VREF+/VREF-(1)							
AD23b	GERR	Gain Error	—	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24b	EOFF	Offset Error	—	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (10-bit Mode)(2)							
HAD33b	FNYQ	Input Signal Bandwidth	—	—	400	kHz	—

Note 1: These parameters are characterized, but are tested at 20 ksps only.

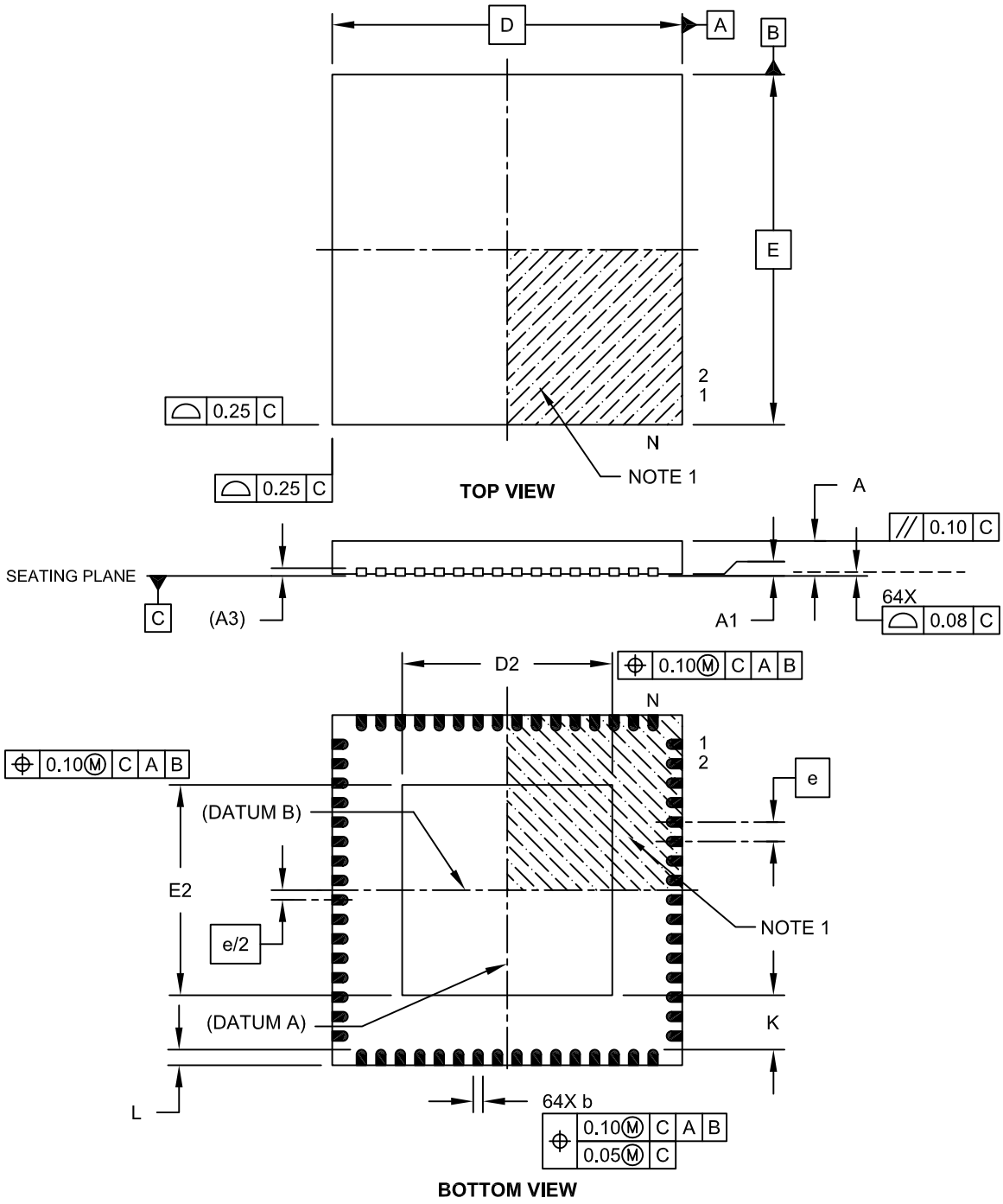
2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

27.2 Package Details

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-154A Sheet 1 of 2